## Electronic Supplimentary Information

## Fair Surface Modification with Mixed Alkanethiols on Gold Nanoparticles through Minimal Unfair Ligand Exchange

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**Figure S1.** TEM images (A) and extinction spectra (B) of 10-nm AuNPs coated with citrate (blue) and OH-EG6 (red) as before and after reaction, respectively. The sizes in the TEM images indicate mean  $\pm$  SD (n = 150 and 340). The numbers in the spectra indicate their peak wavelength.

**Table S1**. Hydrodynamic diameter and zeta-potential of AuNPs before and after surface modifications withC1-, C2-, and OH-EG6-C11-SH ligands.

Surface modifier	Zeta-Potential (mv)	Size <sup>*1</sup> (nm)	
Citrate	-27.1	10.6	
C1-EG6-C11-SH	-4.4	12.4	
C2-EG6-C11-SH	-3.7	14.8	
OH-EG6-C11-SH	-5.0	12.9	

\*1 Size was determined as a main peak size in DLS size distribution by volume.



**Figure S2.** Extinction peak shifts of AuNPs@C2-EG6-C11-SH (blue) and AuNPs@pNIPAM-SH (red) upon heating. Thermo-responsive properties of AuNPs@pNIPAM-SH were measured in 20 mM NaCl aq.



**Figure S3**. Thermo-responsive phenomena of AuNPs modified with (A) C1-EG6-C11-SH and (B) OH-EG6-C11-SH upon heating. Extinction spectra (left) and size distribution by DLS (right).



**Figure S4.** (A) Extinction spectra and (B) size distribution of AuNPs purified after measurements in Figure 2A in the absence of free alkane-thiols upon heating. (C) Extinction spectra and (D) Size distribution of AuNPs@C2-EG6-C11-SH upon heating in the presence of OH-EG6-C12.



**Figure S5.** (A) Size distribution of C1-EG6-C11-SH-replaced AuNPs@C2-EG6-C11-SH determined by DLS and (B) comparison of thermo-responsive assembly temperatures of AuNPs@C2-EG6-C11-SH (blue), AuNPs@C2-EG6-C11-SH heated in the presence of C1-EG6-C11-SH at 85°C for 0.5 h (red), and AuNPs@C1-EG6-C11-SH (green).



**Figure S6.** (A) Schematic illustration of the recovery of thermo-responsiveness by addition of C2-EG6-C11-SH as free ligands. (B) Size distribution of 10-nm AuNPs@C2-EG6-C11-SH reacted with OH-EG6-C11-SH after purification (left) and AuNPs further reacted with C2-EG6-C11-SH (right).



**Figure S7**. (A) Peak wavelength of 10-nm AuNPs@C2-EG6-C11-SH at each temperature over four cycles of heating. (B) Size distribution of the AuNPs after spectral measurement.



**Figure S8**. Reaction time-dependent changes in their thermo-responsive temperature of AuNPs@OH-EG6-C11-SH reacted with C2-EG6-C11-EG6 at 85°C. Size distribution at each reaction time: (A) before addition regarded as 0 minutes, (B) 3 min, (C) 5 min, (D) 30 min, (E) 60 min, and (F) 180 min. (E) Plot of assembly temperature at each time.



**Figure S9**. Reaction time-dependent changes in their thermo-responsive temperature of AuNPs@C1-EG6-C11-SH reacted with C2-EG6-C11-EG6 at 85°C. Size distribution at each reaction time: (A) before addition regarded as 0 minutes, (B) 5 min, (C) 30 min, (D) 60 min, and (E) 180 min. (F) Plot of assembly temperature at each time.



**Figure S10**. Reaction time-dependent changes in their thermo-responsive temperature of AuNPs@C2-EG6-C11-SH reacted with C1-EG6-C11-EG6 at 85°C. Size distribution at each reaction time: (A) before addition regarded as 0 minutes, (B) 5 min, (C) 30 min, (D) 60 min, and (E) 180 min. (F) Plot of assembly temperature at each time.



**Figure S11**. Assembly temperature changes (left) and ligand content changes at the AuNP surface (right) in the time-course experiment for10-nm AuNPs@OH-EG6-C11-SH reacted with C2-EG6-C11-SH at (A) 55°C and (B) 25°C.



**Figure S12**. Assembly temperature in the time-course experiment for 10-nm AuNPs@C1-EG6-C11-SH by addition of C2-EG6-C11-SH at the ligand exchange temperature of 85°C, 55°C, and 25°C.



**Figure S13**. Thermo-responsive size distribution of (A) AuNPs@C2-EG6-C11-SH incubated for various times at 25°C.



**Figure S14**. Assembly temperature changes in the time-course experiment for 10-nm AuNPs@ (50% OH-EG6-C11-SH + 50% C2-EG6-C11-SH) in the presence of a mixture of C2-EG6-C11-SH and OH-EG6-C11-SH at the same concentration at  $25^{\circ}$ C (A) within 24 hours and (B) over 24 hours.



**Figure S15**. Assembly temperature change in 10-nm AuNPs modified with the mixed ligands of 50% C2-EG6-C11-SH + 50% OH-EG6-C11-SH upon heating at 85°C for 3 hours in the presence of the identical free ligands.

**Table S2**. Assembly temperature of 10-nm AuNPs modified with the mixed ligands at various ratios: (A)C1-EG6-C11-SH and C2-EG6-C11-SH and (B) OH-EG6-C11-SH and C2-EG6-C11-SH.

## **(A)**

C2-EG6-C11-SH (%)	100	75	50	25	0
C1-EG6-C11-SH (%)	0	25	50	75	100
<i>T</i> <sub>A</sub> (°C) <sup>*1</sup>	37.0 ± 1.0	45.7 ± 1.2	56.0 ± 1.7	66.0 ± 1.0	77.7 ± 1.2

## **(B)**

C2-EG6-C11-SH (%)	90	80	70	60	50
OH-EG6-C11-SH (%)	10	20	30	40	50
<i>T</i> <sub>A</sub> (°C) <sup>*1</sup>	40.7 ± 0.6	47.0 ± 1.0	55.3 ± 2.1	63.7 ± 2.5	74.8 ± 2.6

\*1  $T_A$  was determined from three independent DLS analyses.